

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of Tong

Serial No. 10/084,869

Filing Date: March 1, 2002

Title: Underfill Encapsulant for Wafer Packaging and Method for its Application

Attorney Docket # 1988.EEM

Examiner: David J. Buttner

Group Art Unit: 1712

Date of this response: May 6, 2005

Commissioner of Patents P.O. Box 1450 Alexandria, VA 22313-1450

AMENDMENT AFTER FINAL REJECTION

Sir,

In response to the Final Rejection mailed on January 7, 2005, for which the time to respond has been extended to May 9, 2005 by the Petition for Extension of Time filed herewith, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims begin on page 3 of this paper.

Remarks begin on page 12 of this paper.